

In the Specification

Please add the following new paragraphs [0023.1], [0023.2], [0023.3] to the end of the BRIEF DESCRIPTION OF THE DRAWINGS, after paragraph [0023] and before the header "DETAILED DESCRIPTION OF THE INVENTION" above paragraph [0024]:

[0023.1] Fig. 11 is an elevation view of a semiconductor die including a first device level having a first pitch, a second device level having a second pitch, and a third device level having a third pitch.

[0023.2] Fig. 12 depicts a schematic diagram representing a memory plane within an exemplary three-dimensional passive element memory array.

[0023.3] Fig. 13 is an electrical schematic of a portion of an exemplary memory array.